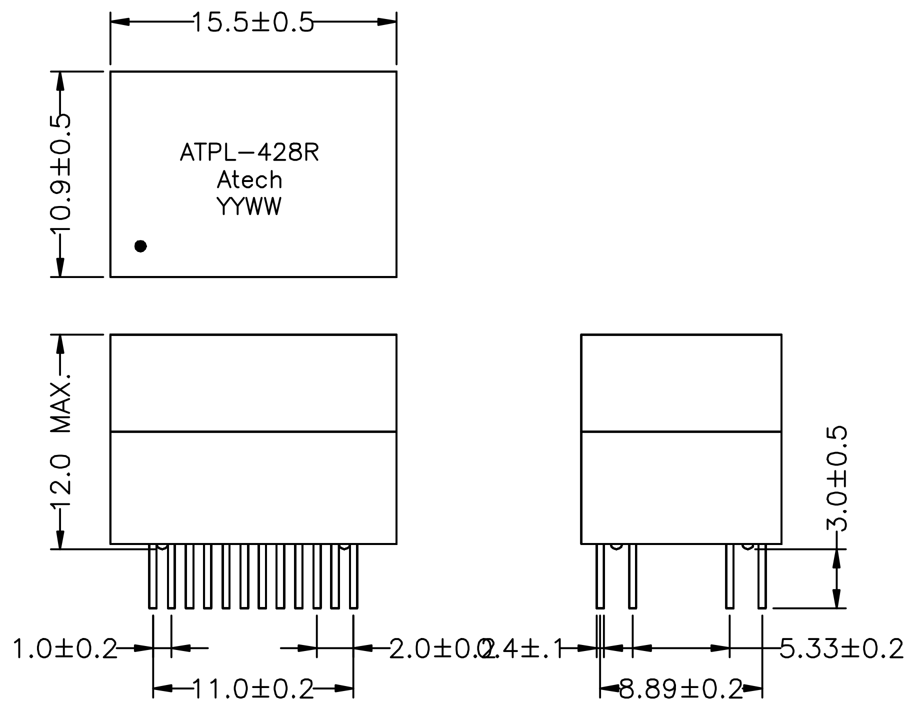
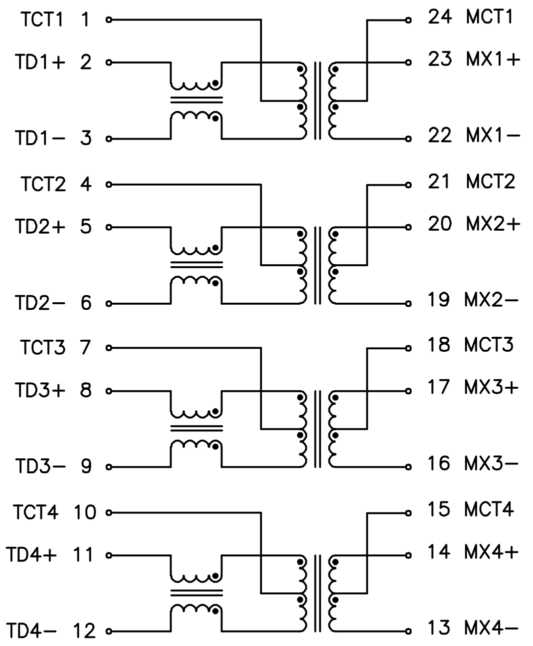
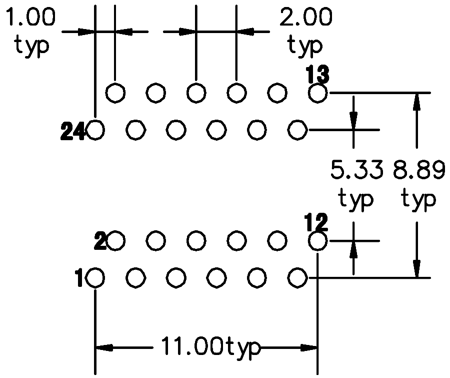






Suggested PAD Layout

ELECTRICAL CHARACTERISTICS @25°C:

1. TURNS RATIO : TX = 1CT : 1CT ± 5%
RX = 1CT : 1CT ± 5%
2. OCL : 350uH MIN.(@100kHz, 0.1V, 8mA DC BIAS)
3. LEAKAGE INDUCTANCE : 0.5uH MAX.(@100kHz, 0.1V)
4. DCR : 1.4Ω MAX.
5. INSERTION LOSS : 1−100MHz = −1.1dB MAX.
6. CROSS TALK : 1−100MHz = −30dB MIN.
7. RETURN LOSS :(@LOAD100 Ω)
1−30MHz= −18dB MIN.
40MHz= −14.4dB MIN.
50MHz= −13.1dB MIN.
60−80MHz = −12dB MIN.
100MHz = −10dB MIN.
8. DCMRR : 1−100MHz = −30dB MIN.
9. HI−POT : 1500Vrms, 1mA, 60SEC
10. RoHS COMPLIANT

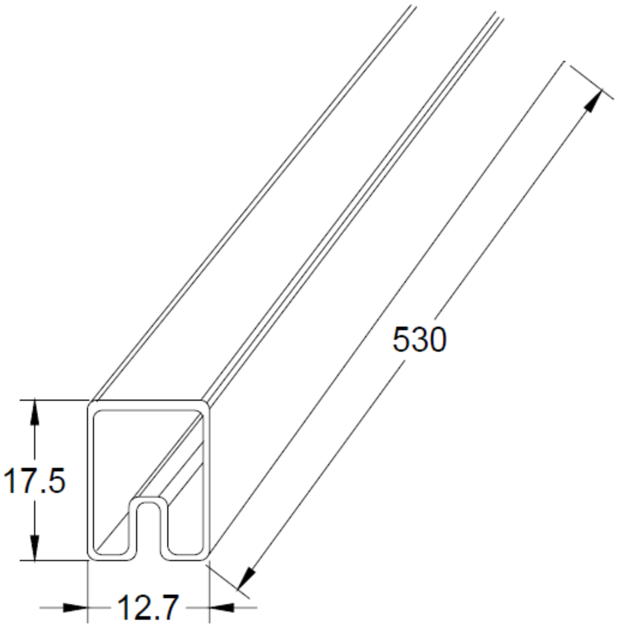
NO:	DESCRIPTION	DATE	BY	CHK	APPD
A	CHANGE EXTERIOR & ELECTRICAL CHARACTERISTICS	06/27/2018	SHIRLEY	BETTY	BETTY
	RELEASE	06/21/2011	SHIRLEY	BETTY	BETTY

REVISIONS

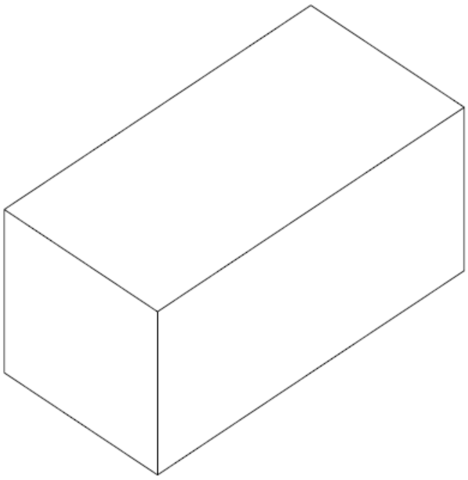
AOEM Atech

TITLE 1000 BASE−T SINGLE PORT TRANSFORMER MODULE
DWG. NO. ATPL−428R
UNITS: M/M
SAFETY
SHEET 1 OF 1
DATE 06/21/11
P/N:
DRAW SHIRLEY

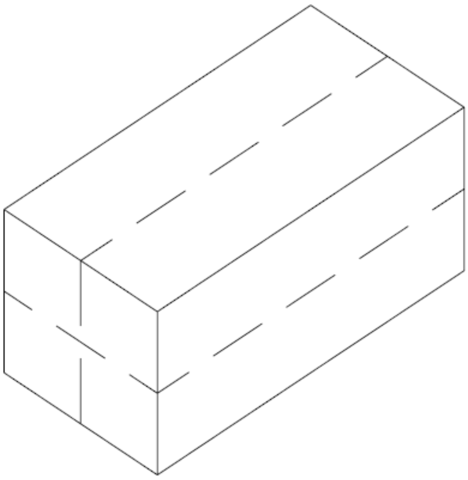
Package :



Tube: 530*17.5*12.7mm



Inner Carton



Export Carton

Package Quantity:

One Tube=32Pcs

One Carton=1600Pcs

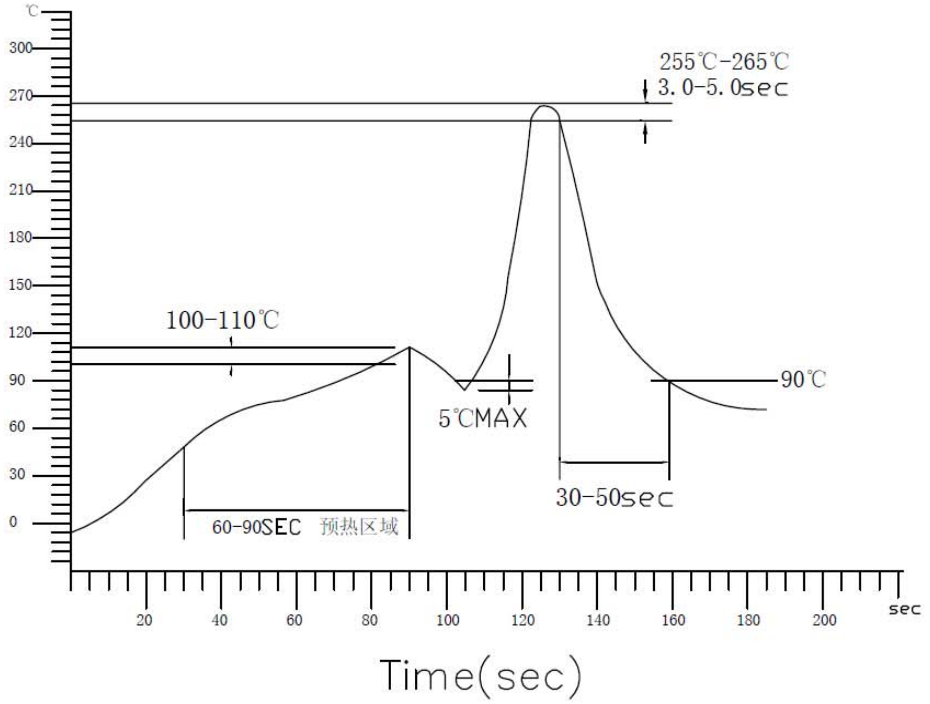
One Export Carton=6400Pcs

6. Soldering Heat Withstanding Survey (DIP)

Pb−free Soldering Heat Withstanding Survey(DIP)

Reflow conditions	Preheat area	Time at 220℃ or higher	Peak Temp	Holding time at 260℃ temp
Recommended conditi	Max 120s	Max 30s	260℃	Max 6S

Soldering Temp.profile



Soldering conditions	Soldering Temp.	Heating Time
Recommended conditions	260℃±5℃	Max 6 sec

Soldering Iron Conditions	Soldering Iron Temp	Heating Time
Recommended conditions	350±10℃	Max 5 sec

Part Electrode Plating Constitution	Sn.CU
Any other series applicable same conditions	NO
Packing Configuration	TRAY